

MECHANICAL CASE OUTLINE

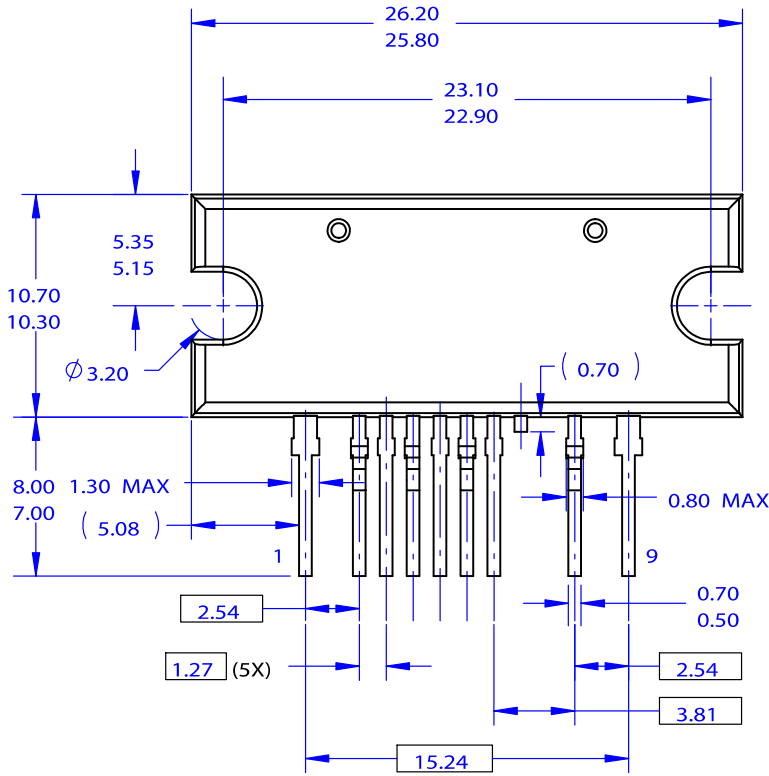
PACKAGE DIMENSIONS

ON Semiconductor®

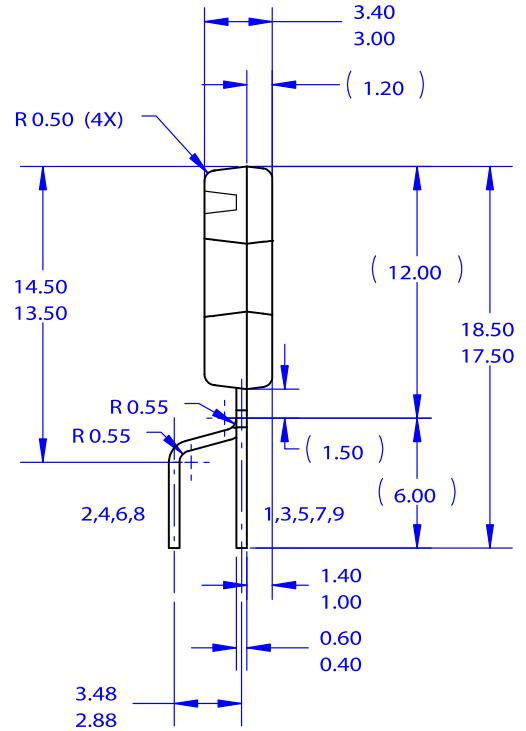


SIP9 26x10.5
CASE 127EM
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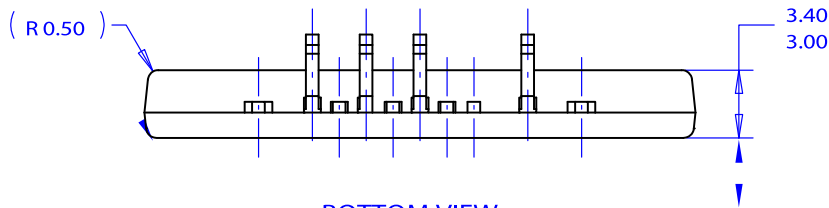
DATE 31 DEC 2016



FRONT VIEW



RIGHT SIDE VIEW



BOTTOM VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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